## 6<sup>th</sup> International Symposium on Tin Whiskers November 27-28, 2012

November 27-28, 2012 Henry Ford College University Way Loughborough LE11 3TL **Tuesday November 27<sup>th</sup>** 

8:00	Registration	
8:10	Welcome To Loughborough	Geoffrey Wilcox, University of Loughborough (UK)
8:20	Open 6 <sup>th</sup> International Symposium on Tin Whiskers	Michael Osterman, CALCE
8:30	Tin Whisker Risk Management for High Reliability Systems	Bob Gregory, Rolls-Royce (UK)
9:00	Manufacturing and In-service Tin Whisker Mitigation Strategies: The Co-deposition of Particulates and Conformal Coating	M.A. Ashworth, University of Loughborough (UK)
9:30	Development of Shape Varieties of Whisker Formations on Bright Tin Layers	Barbara Horváth, National Institute for Materials Science (Hungary)
10:00	Break	(Hungary)
10:15	Tin Whisker and Hillock Growth via Grain Boundary Sliding Coupled with Shear Induced Grain Boundary Migration	Pylin Sarobol, Purdue University (USA)
11:00	Thermal Cycling Whiskers and Influence of Atmosphere	K. Sugunuma, Osaka University
11:30	Increased Shorting in Sn Whiskers due to Electric Fields and Contact Pressure	Martin Wickham, NPL (UK) and Barrie Dunn, ESA (Netherlands)
12:00	Lunch	(
1:00	Whisker Growth in Low and High Stress Environments: Metallurgical Assessment and Statistical Analysis – Part 1	Polina Snugovsky, Celestica (Canada)
2:00	Whisker Growth in Low and High Stress Environments: Metallurgical Assessment and Statistical Analysis – Part 2	Steph Meschter, BAE (USA)
2:45	Break	
3:00	A Solution to Tin Whiskers by Hot Solder Dipping	Mark Walmsley, Micross Components (UK)
3:30	A Cure for Tin Whiskers by Re-passivation	Michael Swanwick, Rolls- Royce (UK)
4:00	Effectiveness of Photosintering in Mitigating Tin Whisker Formation	Michael Osterman, CALCE (USA)
4:45	Adjourn	. ,

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Wednesday November 28 <sup>th</sup>			
8:00	Welcome	Michael Osterman, CALCE	
8:15	Electrical Aspects of Zinc and Tin Metal Whisker Induced Failures In Electronic Equipment	(USA) Michael Osterman, CALCE (USA)	
8:45	Novel Nanoparticle Enhanced Conformal Coating for Whisker Mitigation	Steph Meschter, BAE (USA)	
9:15	The Mitigation of Tin Whiskers by Optimization of Electroplating Process Methodologies	M.A. Ashworth, Loughborough University (UK)	
<b>10:00</b> 10:30	<b>Break</b> An Investigation into the Role of Lead as a Suppressant for Tin Whisker Growth in Electronics	Jing (Jacob) Wang, Loughborough University (UK)	
11:00	Study if Tin Whisker Inhibiting Systems Controlling the Copper Substrate Roughness Controlling The Tin Deposit Crystal Structure	George Milad, Uyemura (USA)	
11:45	Adjourn		

## Wednesday November 28<sup>th</sup> (Afternoon 1:00-5:00 pm)

12:45 **Registration** 

1:00 Short Course Tin Whisker Failure Risk and Mitigation Strategies Michael Osterman, CALCE (USA)